

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ANALOG MEMS SENSORS/26/16638	
1.3 Title of PCI	New Wafer introduction for Ring Removal transfer from FE to BE (OD0C).	
1.4 Product Category	Pls refer to the impacted Products List	
1.5 Issue date	2026-10-21	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Max Brambilla
2.1.2 Marketing Manager	Fabio CHELLI
2.1.3 Quality Manager	Alessandro PLATINI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Change in separation process from single wafer to die (change from sawing to laser cut, etc..)	CARSEM S

4. Description of change

	Old	New
4.1 Description	Ring Removal in Catania CT8 FE Fab.	Ring Removal in CARSEM S BE Fab.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	FE Capacity Improvement
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	New FGs
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7. Timing / schedule

7.1 Date of qualification results	2026-09-30
7.2 Intended start of delivery	2026-11-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16638 Reliability Report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-10-21

9. Attachments (additional documentations)

16638 Public product.pdf
16638 Reliability Report.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	POWERSTEP01	
	POWERSTEP01TR	

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